



Final Product Change Notification

201909023F01

Issue Date: 27-Oct-2019

Effective Date: 24-Jan-2020

Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



Management Summary

LPC540xx will be sourced from die revision 1B.

Change Category

- | | | | | |
|--|---|--|---|---|
| ☐ Wafer Fab Process | ☐ Assembly Process | ☐ Product Marking | ☐ Test Location | ☒ Design |
| ☐ Wafer Fab Materials | ☐ Assembly Materials | ☐ Mechanical Specification | ☐ Test Process | ☐ Errata |
| ☐ Wafer Fab Location | ☐ Assembly Location | ☐ Packing/Shipping/Labeling | ☐ Test Equipment | ☐ Electrical spec./Test coverage |
| ☐ Firmware | ☐ Other | | | |

LPC540xx Revision
Change from 0A to
1B

Description of Change

Microcontroller products LPC540xx will be sourced from the new product revision 1B to resolve multiple errata items.

Product revision 1B resolves the following errata as described in the device errata sheet, https://www.nxp.com/docs/en/errata/ES_LPC540xx.pdf

ISP.1, OTP.1, OTP.2, USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1.

Reason for Change

To fix the functional deviations ISP.1, OTP.1, OTP.2, USB.1, USB.3, IOCON.1, ROM.1 and USB.ROM.1 as documented in the errata sheet.

Identification of Affected Products

Top side marking

The last 2 characters of the last line in the top side marking changes from "0A" to "1B"

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 28-Dec-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No change to form, fit or function other than the fixed errata items

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 25-Nov-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager

e-mail address tim.camenzind@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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